

-	259	encapsulated) near2 thickness (((sealing adj resin) encapsulating encapsulated) near2 thickness) and (chip device die)	USPAT	2000/11/30 13:40
-	48	(((sealing adj resin) encapsulating encapsulated) near2 thickness) near5 (chip device die)	USPAT	2001/06/14 08:23
-	4	((("5844168") or ("5642261") or ("5525834") or ("5683942"))).PN.	USPAT	2000/11/30 15:30
-	0	((("4996587") or ("5672909") or ("5796170"))).PN.	USPAT	2000/11/30 15:30
-	1410	257/723	USPAT	2000/12/01 16:32
-	1142	257/724	USPAT	2000/12/01 16:32
-	1865	257/723 257/724	USPAT	2000/12/01 16:32
-	881	(257/723 257/724) and lead and substrate	USPAT	2000/12/01 16:33
-	139	((257/723 257/724) and lead and substrate) and multichip	USPAT	2000/12/01 16:44
-	135	((257/723 257/724) and lead and substrate) and (chip near1 chip)	USPAT	2000/12/01 16:45
-	94	((257/723 257/724) and lead and substrate) and (chip near1 chip)) not ((257/723 257/724) and lead and substrate) and multichip)	USPAT	2000/12/01 16:46
-	3	(multichip near1 package) and ((flexible near (substrate tape insulation)) with (conductive near trace))	USPAT; EPO; JPO; DERWENT	2001/06/14 08:32
-	81	((sealing adj resin) encapsula\$4) near2 thickness) near5 (chip device die)	USPAT	2001/06/14 08:25
-	95	((sealing adj resin) encapsula\$4) near2 thickness) near5 (chip device die)	USPAT; US-PGPUB; EPO; JPO	2001/06/14 08:26
-	1	(((((sealing adj resin) encapsula\$4) near2 thickness) near5 (chip device die)) and (flexible near1 (lead trace conductive)) (multichip near1 package) and ((flexible near (substrate tape insulation)) with (conductive near trace))	USPAT; US-PGPUB; EPO; JPO	2001/06/14 08:29
-	4	(multichip near1 package) and ((flexible near (substrate tape insulation)) with (conductive near trace))	USPAT; EPO; JPO; DERWENT	2001/06/14 08:33
-	71	(second near1 chip) with (heat near2 (conducting releasing radiator sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 13:39
-	82	(second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 15:02
-	1	6156980.URPN.	USPAT	2002/05/14 13:51
-	5	("5352926" "5710071" "5777386" "5969461" "5973927").PN.	USPAT	2002/05/14 13:51
-	1	"5086431".PN.	USPAT	2002/05/14 14:10
-	2	5638391.URPN.	USPAT	2002/05/14 14:11
-	22	5323292.URPN.	USPAT	2002/05/14 14:16
-	40	("3324224" "4313492" "4335781" "4480262" "4561040" "4603374" "4727455" "4740866" "4806503" "4825284" "4888449" "4897508" "4912548" "4939316" "4949219" "4961106" "4967260" "5015803" "5018005" "5023398" "5025114" "5055967" "5066368" "5073521" "5103292" "5175613" "5184211" "5189505" "5214308" "5216283" "5235209" "5256205" "5284706" "5291064" "5323292" "5324569" "5334857" "5352926" "5353193"	USPAT	2002/05/14 14:44

	"4763188" "4982265" "5025306"		
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	"5176311" "5177032" "5198888"		
	"5291060" "5291061" "5323060"		
	"5384689" "5432729" "5620928"		
	"5682062" "5721452" "5739581"		
	"5815372" "5872025" "5886412"		
	"5989982" "6013948" "6030855"		
	"RE36613" "6033931" "6049094"		
	"6051886" "6057598" "6087722"		
	"6133637" "6201302" "6204091"		
	"6215182" "6229217").PN.		
-	187 ((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 15:01
-	165 ((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink))) not ((second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 15:02
-	112 (((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink))) not ((second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink)))) and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 15:56
-	2 ("5866949" "5925934").PN.	USPAT	2002/05/14 15:09
-	0 6201266.URPN.	USPAT	2002/05/14 15:09
-	16 5199165.URPN.	USPAT	2002/05/14 15:19
-	16 5199165.URPN.	USPAT	2002/05/14 15:22
-	13 ("2350348" "3361195" "3564109" "4047198" "4327399" "4519447" "4631636" "4727454" "4859520" "4878152" "4967314" "4994215" "5095359").PN.	USPAT USPAT USPAT USPAT	2002/05/14 15:22
-	37 4862322.URPN.	USPAT	2002/05/14 15:26
-	41 5438224.URPN.	USPAT	2002/05/14 15:40
-	0 6313527.URPN.	USPAT	2002/05/14 15:41
-	2 ("5438224" "6072243").PN.	USPAT	2002/05/14 15:41
-	3 6137164.URPN.	USPAT	2002/05/14 15:44
-	15 ("3577037" "5347162" "5438224" "5468681" "5477160" "5483421" "5759047" "5786628" "5815374" "5918113" "5958590" "5965064" "5977640" "5984691" "6013948").PN.	USPAT USPAT	2002/05/14 15:45
-	53 (((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink))) not ((second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink)))) not (((second adj chip) and (heat near2 (conducting conductive release releasing radiator sink))) not ((second near1 chip) with (heat near2 (conducting conductive release releasing radiator sink)))) and (wire wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 16:01
-	1570 noise near shield\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/05/14 16:03
-	0 257/685,686,723,724,777	USPAT; US-PGPUB; EPO; JPO;	2002/05/14 16:05

-		EPO; JPO; DERWENT USPAT	2002/05/14 16:07
-	4	("5677575" "5757078" "5821625" "5869903").PN.	
-	6	5821625.URPN.	USPAT 2002/05/14 16:08
-	6	5821625.URPN.	USPAT 2002/05/14 16:11
-	5	("4763188" "4811082" "5508565" "5596225" "5656856").PN.	USPAT 2002/05/14 16:11
-	6	(noise near shield\$3) and ((chip adj1 chip) (dual adj dies adj packag\$3))	USPAT; 2002/05/14 16:19 US-PGPUB; EPO; JPO; DERWENT
-	6	((noise near shield\$3) and ((chip adj1 chip) (dual adj dies adj packag\$3))) not ((noise near shield\$3) and 257/685,686,723,724,777.ccls.)	USPAT; 2002/05/14 16:20 US-PGPUB; EPO; JPO; DERWENT
-	5	(noise near shield\$3) and (stacked with (chip semiconductor (integrated adj circuit)))	USPAT; 2002/05/14 16:22 US-PGPUB; EPO; JPO; DERWENT
-	2	(aln (aluminum adj nitride)) near3 (solder adj (bump ball))	USPAT; 2002/05/28 13:58 US-PGPUB; EPO; JPO; DERWENT
-	41	(aln (aluminum adj nitride)) near3 (bump ball)	USPAT; 2002/05/28 13:59 US-PGPUB; EPO; JPO; DERWENT
-	8	((solder adj (bump ball)) near2 copper) and ((wiring adj layer) near2 copper)	USPAT; 2002/05/29 10:10 US-PGPUB; EPO; JPO; DERWENT
-	13	(load near2 copper) and ((wiring adj layer) near2 copper)	USPAT; 2002/05/29 10:12 US-PGPUB; EPO; JPO; DERWENT
-	21	(electrode near2 copper) and ((wiring adj layer) near2 copper)	USPAT; 2002/05/29 10:12 US-PGPUB; EPO; JPO; DERWENT
-	60	"5477082"	USPAT; 2002/05/29 12:27 US-PGPUB; EPO; JPO; DERWENT
-	47	"5438224"	USPAT; 2002/05/29 12:27 US-PGPUB; EPO; JPO; DERWENT
-	15	"4703483"	USPAT; 2002/05/29 12:32 US-PGPUB; EPO; JPO; DERWENT
-	11	"5719436"	USPAT; 2002/05/29 12:34 US-PGPUB; EPO; JPO; DERWENT
-	129	"5477082" "5438224" "4703483" "5719436"	USPAT; 2002/05/29 12:34 US-PGPUB; EPO; JPO; DERWENT
-	7	("5065505" "5396403" "5477082" "5977640" "6075287" "6133637" "6150724").PN.	USPAT 2002/05/29 12:39
-	11	("5471369" "5646829" "5719436" " " "	USPAT 2002/05/29 12:42

	"3778886"	"3813650"	"3813773"		
	"3983619"	"3999105"	"4300153"		
	"4387503"	"4426773"	"4525921"		
	"4598462"	"4612083"	"4613891"		
	"4646128"	"4659931"	"4672737"		
	"4677528"	"4703170"	"4706166"		
	"4761681"	"4764846"	"4783695"		
	"4801992"	"4803595"	"4807021"		
	"4827327"	"4862249"	"4894706"		
	"4897708"	"4901136"	"4907128"		
	"4939568"	"4941033"	"4954875"		
	"4956694"	"4956695"	"4956746"		
	"4959749"	"4983533"	"4989063"		
	"4996583"	"5006923"	"5013687"		
	"5019943"	"5025306"	"5028986"		
	"5032896"	"5055425"	"5075253"		
	"5093708"	"5104820"	"5111278"		
	"5117282"	"5128831"	"5135556"		
	"5138437"	"5138438"	"5172303"		
	"5191404"	"5191405"	"5198888"		
	"5200300"	"5202754"	"5221642"		
	"5222014"	"5229647"	"5231304"		
	"5247423"	"5259110"	"5270261"		
	"5270571"	"5279029"	"5279984"		
	"5283107"	"5311401"	"5330359"		
	"5377077"	"5420751"	"5446620"		
	"5455740"	"5475920"	"5479318"		
	"5493476"	"5499160"	"5502333"		
	"5532614"	"5543664"	"5550711"		
	"5552963"	"5561591"	"5566051"		
	"5827759"	"5844296"	"5853603") .PN.		
13	("4724427"	"4857893"	"5023624"	USPAT	2002/10/10 10:25
	"5202752"	"5345231"	"5717231"		
	"5764655"	"5929825"	"5999409"		
	"6096496"	"6161205"	"6181001"		
	"6201296") .PN.				
12	"6054337"			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:05
4	"5894166"			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:05
17	"5898223"			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:05
10	"6147401"			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:05
2	"6414396"			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:05
41	"6054337" "5894166" "5898223" "6147401" "6414396"			USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:06
0	6355977.URPN.			USPAT	2002/10/10 13:09
10	("5757179" "5834844" "5898223" "5903044" "5960308" "5976953" "5977641" "6002163" "6005262"			USPAT	2002/10/10 13:09

		"5923091" "5946545" "5995379" "6057598").PN.		
-	18	6057598.URPN.	USPAT	2002/10/10 13:19
-	8	("5294826" "5341979" "5367765" "5506756" "5532512" "5610442" "5724230" "5786635").PN.	USPAT	2002/10/10 13:23
-	10	("5243208" "5386623" "5717245" "5783870" "5894166" "5923090" "5923091" "5946545" "5995379" "6057598").PN.	USPAT	2002/10/10 13:28
-	2	6255736.URPN.	USPAT	2002/10/10 13:28
-	6	("4764804" "5034345" "5480834" "5534465" "5585282" "5726500").PN.	USPAT	2002/10/10 13:29
-	3106	(digital analog) near cell	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:43
-	21	((digital analog) near cell) near3 (chip dram)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 13:44
-	48	((digital logic) near cell) with (analog near cell)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:32
-	5	((digital logic) near cell) with (analog near cell)) with (chip dram)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:26
-	0	6460172.URPN.	USPAT	2002/10/10 13:48
-	11	("4402044" "5197016" "5361373" "5384275" "5402358" "5425036" "5438681" "5581742" "5959871" "6006022" "6014509").PN.	USPAT	2002/10/10 13:48
-	9138	(multichip adj module) mcm	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:48
-	25628	(digital logic input output analog) near cell	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:46
-	104	((multichip adj module) mcm) and ((digital logic input output analog) near cell)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:35
-	103	((multichip adj module) mcm) and ((digital logic input output analog) near cell)) not ("6054337" "5894166" "5898223" "6147401" "6414396")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:36
-	43	((multichip adj module) mcm) and ((digital logic input output analog) near cell)) not ("6054337" "5894166" "5898223" "6147401" "6414396")) and (wire wiring) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:36
-	7794	(digital logic analog) near1 cell	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 14:47
-	14778	(multichip adj module) mcm (second near1 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 16:02
-	106	((digital logic analog) near1 cell) and	USPAT;	2002/10/10 14:52

	chip))) not (((multichip adj module) mcm) and ((digital logic input output analog) near cell))	EPO; JPO; DERWENT	
73	((((digital logic analog) near1 cell) and ((multichip adj module) mcm (second near1 chip))) and (ram dram)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 15:28
36	(((((digital logic analog) near1 cell) and ((multichip adj module) mcm (second near1 chip))) and (ram dram)) not (((digital logic analog) near1 cell) and ((multichip adj module) mcm (second near1 chip))) not (((multichip adj module) mcm) and ((digital logic input output analog) near cell)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 15:28
48	(US-6137164-\$ or US-5793115-\$ or US-4862322-\$ or US-6344683-\$ or US-6156980-\$ or US-5533256-\$ or US-5638391-\$ or US-5323292-\$ or US-6052284-\$ or US-5608610-\$ or US-5578869-\$ or US-5214308-\$ or US-6340842-\$ or US-6201302-\$ or US-6225688-\$ or US-6201266-\$ or US-5199165-\$ or US-4774632-\$ or US-6292366-\$ or US-6069025-\$ or US-5539250-\$ or US-5438224-\$ or US-6313527-\$ or US-6080931-\$ or US-6072243-\$ or US-6232668-\$).did. or (US-5821625-\$ or US-6285076-\$ or US-6020867-\$ or US-5668040-\$ or US-6376917-\$ or US-6316822-\$ or US-5719436-\$ or US-5477082-\$ or US-6433398-\$ or US-6373447-\$ or US-6356958-\$ or US-6308143-\$ or US-6255736-\$ or US-6057598-\$ or US-5386623-\$ or US-5243208-\$ or US-6202183-\$ or US-6460172-\$).did. or (US-20020033526-\$ or US-20020130342-\$ or US-20020078278-\$ or US-20020006054-\$).did.	USPAT; US-PGPUB	2002/10/10 15:33
13	("4484292" "5222293" "5249134" "5251147" "5267176" "5381343" "5471398" "5481473" "5613102" "5638293" "5666288" "5712794" "5901066").PN.	USPAT	2002/10/10 15:39
7	5793115.URPN.	USPAT	2002/10/10 15:44
1	6208545.URPN.	USPAT	2002/10/10 15:45
32	("4070230" "4131985" "4416064" "4539068" "4585991" "4612083" "4617160" "4618397" "4618763" "4702936" "4706166" "4721938" "4761681" "4784721" "5070026" "5071510" "5130894" "5236118" "5262351" "5273940" "5284796" "5385632" "5424920" "5426072" "5432729" "5457879" "5502667" "5534466" "5581498" "5637536" "5760478" "5793115").PN.	USPAT	2002/10/10 15:46
14778	((multichip adj module) mcm) (second near1 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 16:09
59	(circuit adj area) near3 ((bond bonding) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 16:10

		(bond bonding) adj pad))	EPO; JPO; DERWENT	
-	2	((circuit adj area) near3 ((bond bonding) adj pad)) and (((multichip adj module) mcm) (second near1 chip)) and (mother adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 16:11
-	26	((multichip adj module) mcm) (second near1 chip)) and (mother adj chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/10 16:12
-	0	20020017718.URPN.	USPAT	2002/10/10 16:13
-	6	("4697095" "5440423" "5640107" "5801547" "5977640" "6049222").PN.	USPAT	2002/10/10 16:14
-	24	4697095.URPN.	USPAT	2002/10/10 16:16
-	5	5446309.URPN.	USPAT	2002/10/10 16:20
-	3	("4697095" "4890077" "5008736").PN.	USPAT	2002/10/10 16:21
-	9	("4055754" "4071902" "4103182" "4350906" "4446390" "4509008" "4550289" "4558447" "4612499").PN.	USPAT	2002/10/10 16:21
-	23	("5072364" "5142634" "5230068" "5287467" "5303356" "5394529" "5428786" "5454117" "5469551" "5508556" "5564118" "5592634" "5623614" "5630157" "5732278" "5760478" "5834835" "5856937" "5903908" "5939782" "5977640" "5994166" "6031284").PN.	USPAT	2002/10/10 16:22